

2827



PATENT
8037-1001

IN THE U.S. PATENT AND TRADEMARK OFFICE

In re application of:

Kimio TSUNEMASU

Confirmation No. 5276

Serial No. 10/073,196

GROUP 2827

Filed February 13, 2002

Examiner James M. Mitchell

SEMICONDUCTOR DEVICE CAPABLE OF
PREVENTING SOLDER BALLS FROM BEING
REMOVED IN REINFORCING PAD

AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

December 11, 2003

Sir:

In response to the Official Action of October 7, 2003,
please amend the above-identified application as follows:

Amendments to the Claims are reflected in the listing
of claims which begins on page 2 of this paper.

Remarks begin on page 6 of this paper.